

## 5

A dielectric film is obtained by heat curing a thermally curable fluorinated o-aminophenol polymer or oligomer based on an o-aminophenol compound and an aromatic dicarboxylic acid compound, at least one of which is mono- or poly-fluorinated, and having thermosetting groups at both ends that undergo cross-linking reaction upon thermal treatment. The dielectric film is employed in multilayer circuit boards.